EMPC 2025 CONFERENCE THE PLACE TO BE

Welcome to EMPC 2025 in Grenoble!

The European Microelectronics and Packaging Conference (EMPC 2025) is the premier international conference for microelectronics packaging, owned and sponsored by IMAPS-Europe and co-sponsored by IEEE-EPS.
The conference program will focus on industrial needs and trends and on academic long-term solutions. The event brings together researchers, innovators, technologists, business and marketing managers with an interest in semiconductor packaging.

Abstract Submission

The content must be original (previously unpublished), non-confidential and non-commercial. Maximum abstract length: 300-500 words. Figures with appropriate captions, and references, can be included, they do not count in the word limit. More information can be found at www.empc2025.org.

DEADLINE
for abstract submission is January 27, 2025

CONTACT

Organised by:

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Conference Venue
World Trade Center of Grenoble
5-7 Pl. Robert Schuman
Grenoble
France

Conference Chair:
Jean-Marc Yannou
Murata, France

Technical Chair:
Dr Stoyan Stoyanov
University of Greenwich, London, UK

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CALL FOR PAPERS

The 25th European Microelectronics & Packaging Conference and Exhibition
15-18 September 2025 Grenoble, France

For more information, visit:
empc2025.org

EMPC 2025 – CONFERENCE TOPICS

Advanced Packaging and System-Integration

- **System in Package**
  New SiP developments, SiP testing; Modules in a package, double sided modules, antenna in package; Chip embedding technologies.
- **IC Packaging**
  Single- and multi-chip packaging, heterogeneous integration, chiplets, WLP, 2.5D/3D-IC, interposers, high-frequency, and high-power packaging, quilt packaging, logic and memory chip integration.
- **Interconnection Technologies**
  Disruptive interconnections, bumping technologies, TSVs and vias; Optical connections, RDLs, 3D printable interconnects.
- **Optoelectronics**
  Assembly and packaging technologies for optical and photonics applications; Co-packaged optics, hybrid and heterogeneous photonics integration; Microscopy, imaging, displays; Equipment and tools.

Specialised Topics

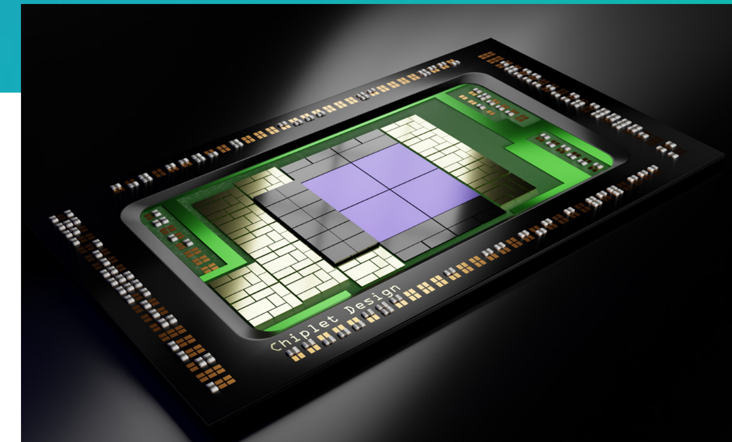
- **Power Electronics**
  Advances in wide-bandgap semiconductor materials and technologies; Si, GaN, SiC packaging, Ag and Cu sintering, SiC wafer sawing, interconnection technologies, test and reliability.
- **Medical Electronics**
  Bio-medical applications, medical devices; Biosensors and bioelectronics; Complying with material and test regulations, and market requirements; Medical imaging.
- **Green Electronics and Sustainability**
  Green and sustainable manufacturing; Renewable energy, solar energy, and photovoltaics technologies; Energy storage, battery technologies; Packaging for improved efficiency of photovoltaic modules; Materials recovery and recycling, Product Carbon Footprint; Sustainability and environment.

Materials and Processes

- **Materials**
  Solder alloys, materials for harsh environments, solder alternatives, conductive/ nonconductive adhesives, encapsulants, smart materials, TIM, high temperature materials.
- **Substrate Technologies**
  Advanced substrate design and technologies, flexible/ stretchable electronics, organic, inorganic, laminates, printed, microfluidics.
- **Assembly & Manufacturing**
  Process development, clean room technologies, process and yield enhancements, micromachining, equipment development.
- **Emerging Technologies**
  Nanotechnology, sensing technologies, MEMS and NEMS, packaging for extreme harsh environments.
- **Smart manufacturing:**
  AI-enabled technologies, Additive Manufacturing, assembly factory automation.

Design, Modelling and Reliability

- **Design, Modelling and Simulation**
  Signal integrity analysis, thermal management, cooling solutions; Electro-magnetic, thermal, and mechanical simulation; Physics-of-failure modelling, virtual qualification, data-driven modelling, model order reduction, optimisation.
- **Inspection and Test**
  New characterisation, inspection and tests methods, measurement and qualification test methodologies, advances in metrology and test equipment; Accelerated life testing, failure detection and analysis; AI for test, standards.
- **Quality and Reliability**
  Quality assurance, monitoring and control, counterfeits; Reliability at component, board and system-level; In-service reliability, prognostics, health management, lifetime models.



Markets and Developments

- **Markets**
  Telecoms (5G/6G), IoT, quantum technologies, computing, mobile, automotive, EVs, aerospace, defence and security, high reliability applications, robotics, consumer, wearables and smart textiles, structural, smart cities.
- **Business Aspects**
  Cost and cycle time reduction, markets and supply chains, distribution, intellectual property, policy issues, obsolescence, business models.
- **Education for Electronics**
  Educational and information technologies for electronics manufacturing, new approaches and standards in electronics education.